

[PACKAGING STRUCTURE WITH HEAT SLUG]

Abstract of Disclosure

A packaging structure comprises a substrate, a chip, a plurality of bonding wires, a heat slug, and a molding compound. The chip is attached and electrically connected onto the substrate. The heat slug includes a concave cover element outwardly extended into a flange, the concave cover element including an outer heat dissipating surface around which a ringed projection is formed. The heat slug is mounted onto the substrate via attaching the flange onto the substrate surface while the concave cover element covers the chip. The molding compound encapsulates the substrate surface, the chip, and the flange of the heat slug while leaving the outer heat dissipating surface of the heat slug externally exposed. Via the ringed projection, the molding compound, when injected to encapsulate the chip, is prevented from flowing over the outer heat dissipating surface of the heat slug.

Figures

